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Product Change Notification - KSRA-28DZLH982 (Printer Friendly)

Date:

05 Apr 2017

Product Category:

Capacitive Touch Sensors; USB Bridge; 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

Notification subject:

CCB 2895 Initial Notice:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 20L QFN package at NSEB assembly site

Notification text:

PCN Status:

Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 20L QFN package at NSEB assembly site.

Pre Change:

Assembled using gold (Au) bond wire.

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB	NSEB
Wire material	Au	CuPdAu
Die attach material	8600	8600

Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	April 2017						→	August 2017				
	13	14	15	16	17	18		31	32	33	34	35
Initial PCN Issue Date		X										
Qual Report Availability												X
Final PCN Issue Date												X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 05, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-28DZLH982_Affected CPN.pdf](#)

[PCN_KSRA-28DZLH982_Qual Plan.pdf](#)

[PCN_KSRA-28DZLH982_Affected CPN.xlsx](#)

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